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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 5) V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	6.0 4.8	A
	t < 10s	T_A = +25°C T_A = +70°C	I_D	7.5 5.9	A
Continuous Drain Current (Note 5) V_{GS} = 4.5V	Steady State	T_A = +25°C T_A = +70°C	I_D	5.0 4.0	A
	t < 10s	T_A = +25°C T_A = +70°C	I_D	6 4.8	A
Maximum Body Diode Forward Current (Note 5)			I_S	2	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	31	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	1.75	W
	T_A = +70°C		1.1	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	72	°C/W
	t < 10s		50	
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	23	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 30V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	1.5	2	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	22	30	mΩ	V_{GS} = 10V, I_D = 7A
		—	32	42		V_{GS} = 4.5V, I_D = 5.6A
Forward Transfer Admittance	$\|Y_{fs}\|$	—	10	—	S	V_{DS} = 5V, I_D = 7A
Diode Forward Voltage	V_{SD}	—	0.75	1.0	V	V_{GS} = 0V, I_S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	498	—	pF	V_{DS} = 15V, V_{GS} = 0V f = 1.0MHz
Output Capacitance	C_{oss}	—	52	—		
Reverse Transfer Capacitance	C_{rss}	—	45	—		
Gate Resistance	R_G	—	2.4	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz
Total Gate Charge	Q_g	—	11.4	—	nC	V_{GS} = 10V, V_{DS} = 15V, I_D = 5.8A
Gate-Source Charge	Q_{gs}	—	1.4	—		
Gate-Drain Charge	Q_{gd}	—	2	—		
Turn-On Delay Time	$t_{D(ON)}$	—	3.4	—	ns	V_{DD} = 15V, V_{GS} = 10V, R_L = 2.6Ω, R_G = 3Ω
Turn-On Rise Time	t_R	—	6.2	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	13.9	—		
Turn-Off Fall Time	t_F	—	2.8	—		

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to production testing.

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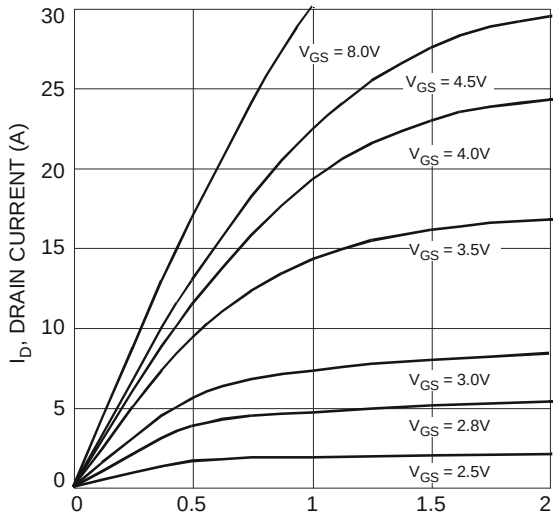

Fig. 1 Typical Output Characteristics

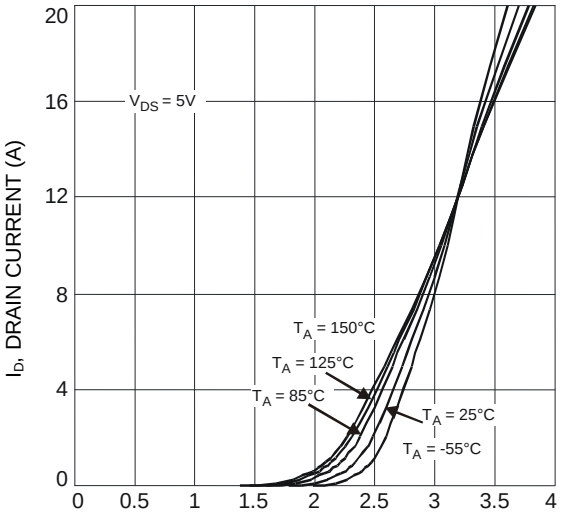

Fig. 2 Typical Transfer Characteristics

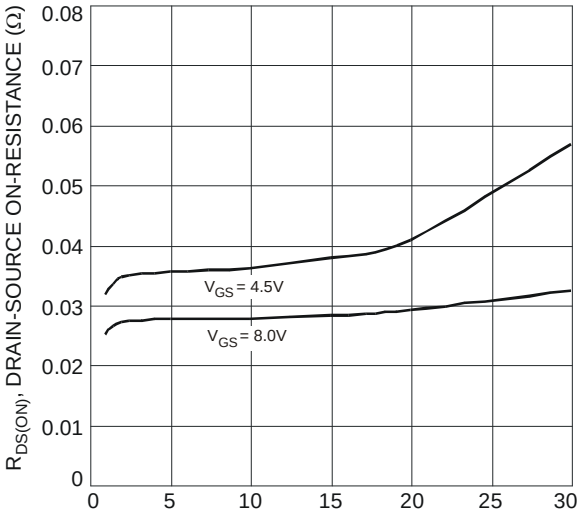

Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

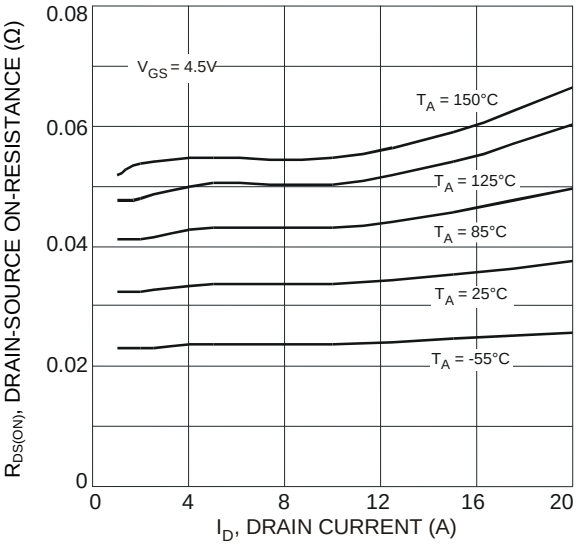

Fig. 4 Typical Drain-Source On-Resistance
vs. Drain Current and Temperature

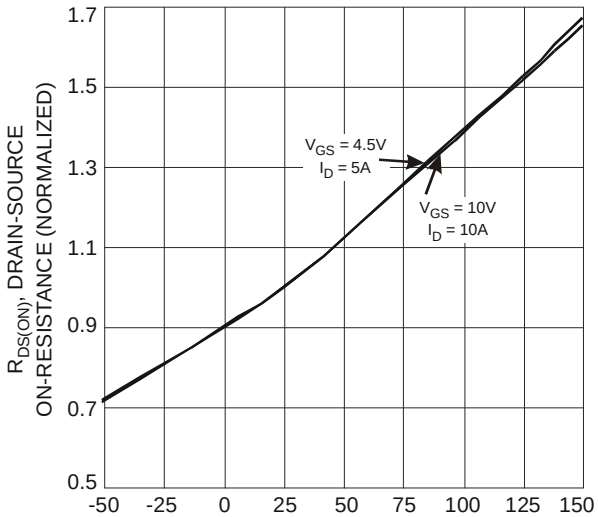

Fig. 5 On-Resistance Variation with Temperature

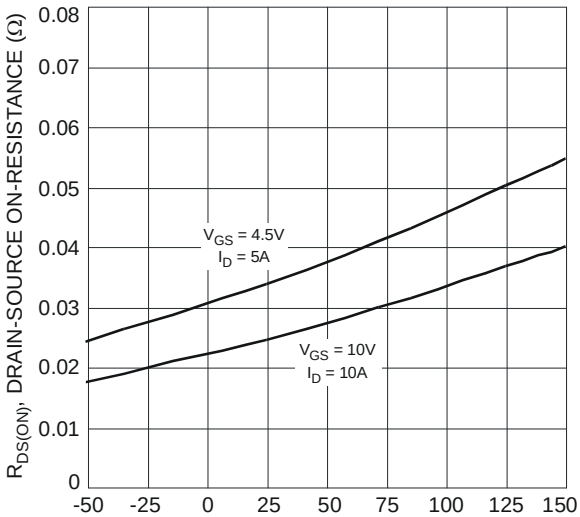

Fig. 6 On-Resistance Variation with Temperature

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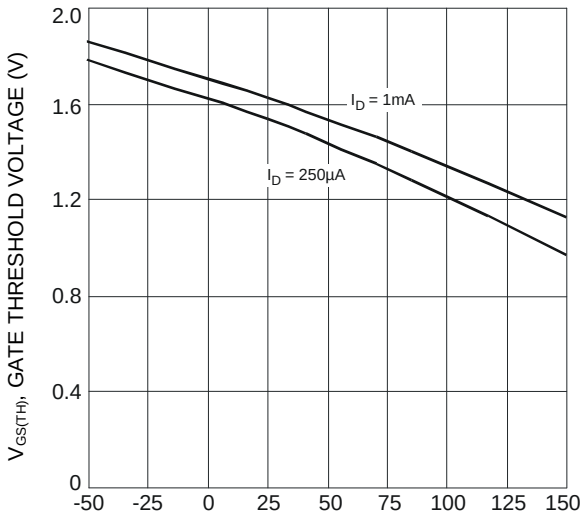

Fig. 7 Gate Threshold Variation vs. Ambient Temperature

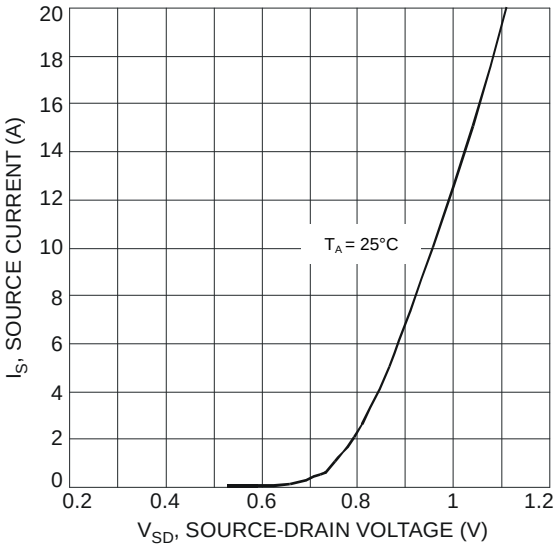

Fig. 8 Diode Forward Voltage vs. Current

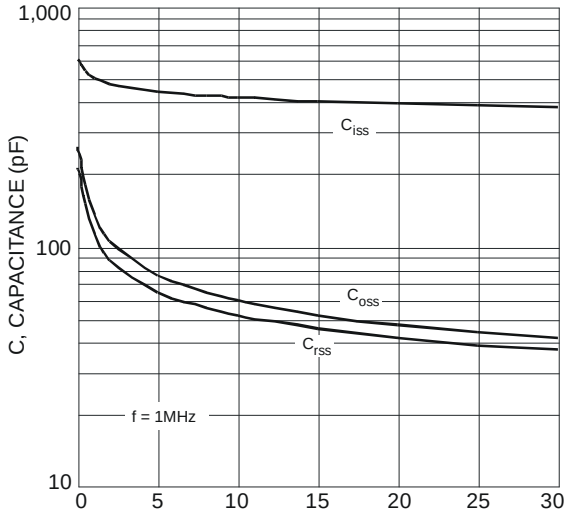

Fig. 9 Typical Capacitance

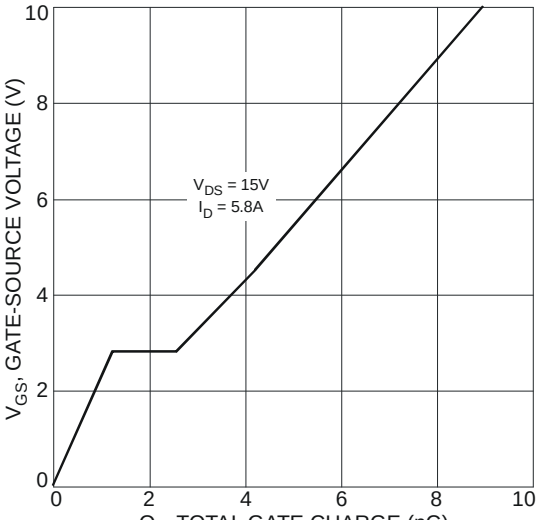

Fig. 10 Gate-Charge Characteristics

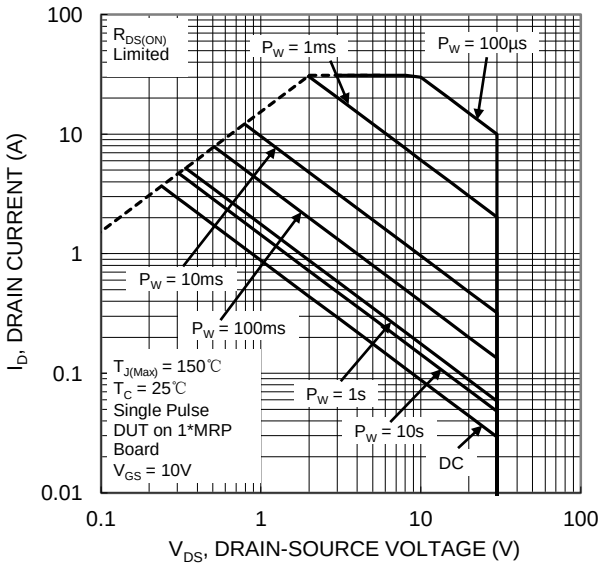

Fig. 11 SOA, Safe Operation Area

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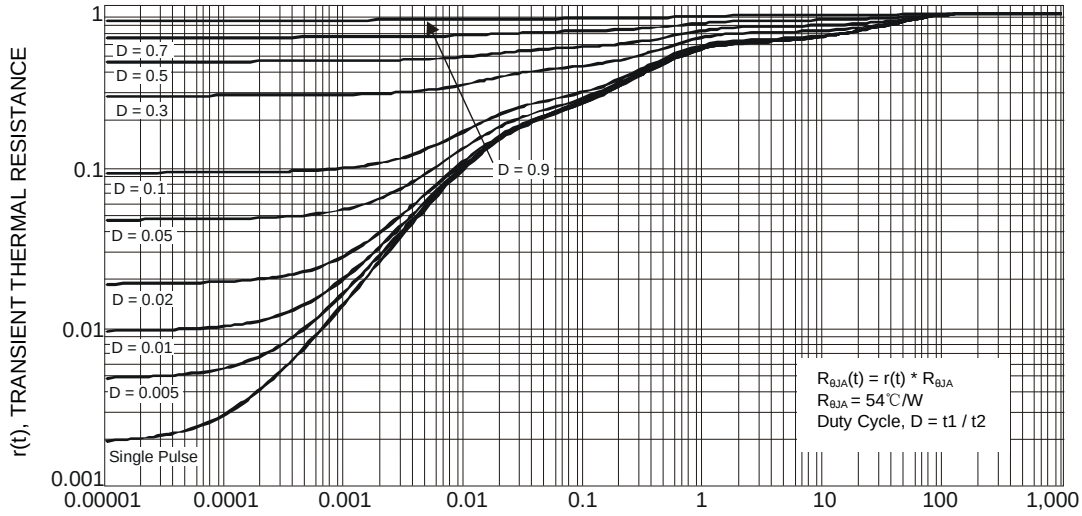

Fig. 12 Transient Thermal Resistance

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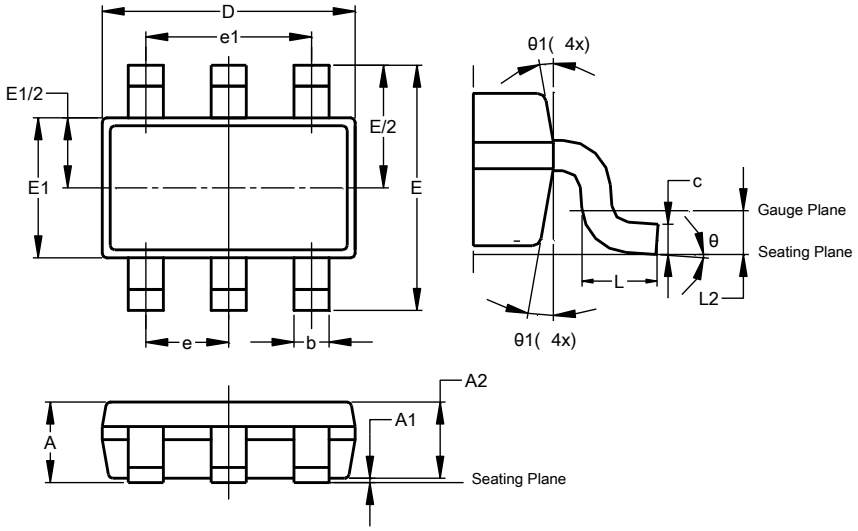
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26

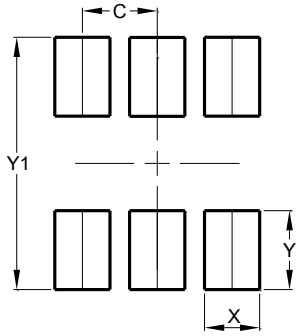


TSOT26			
Dim	**Min**	**Max**	**Typ**
A	–	1.00	–
A1	0.010	0.100	–
A2	0.840	0.900	–
D	2.800	3.000	2.900
E	2.800 BSC		
E1	1.500	1.700	1.600
b	0.300	0.450	–
c	0.120	0.200	–
e	0.950 BSC		
e1	1.900 BSC		
L	0.30	0.50	–
L2	0.250 BSC		
θ	0°	8°	4°
θ1	4°	12°	–
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

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